PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Uway Tseng	06/26/2009
Lin-June Wu	07/07/2009
Yu-Ting Lin	06/26/2009

RECEIVING PARTY DATA

Name:	Taiwan Semiconductor Manufacturing Company, Ltd.
Street Address:	No. 8, Li-Hsin Road 6
City:	Hsin-Chu
State/Country:	TAIWAN
Postal Code:	300-77

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12511789

CH $40.00 12511789

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	24061.1279
NAME OF SUBMITTER:	Liem T. Do

Total Attachments: 2
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Docket No.: 2009-0123 / 24061.1279
Customer No.: 42717

ASSIGNMENT

WHEREAS, we,

(1) Uway Tseng of No. 20-1, 136 Alley, Xin-Sheng Street
Dong-Shi Town, Tai-Zhong Country, Taiwan, R.O.C.

(2) Lin-June Wu of No. 28, Alley 278, Tei-Tow Road, Sec. 2
Hsin-Chu City, Taiwan, R.O.C.

(3) Yu-Ting Lin of 8F-1, No. 523, Nan-Da Road
Hsin-Chu City, Taiwan, R.O.C.

have invented certain improvements in

CMOS IMAGE SENSOR BIG VIA BONDING PAD APPLICATION FOR AlCu PROCESS

for which we have executed an application for Letters Patent of the United States of America,

_______ of even date filed herewith; and
XX filed on 7-29-2009 and assigned application number ____________ and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar ($1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Uway Tseng

Residence Address: No. 20-1, 136 Alley, Xin-Sheng Street
Dong-Shi Town, Tai-Zhong Country, Taiwan, R.O.C.

Dated: June 26, 2009

Uway Tseng
Inventor Signature

Inventor Name: Lin-June Wu

Residence Address: No. 28, Alley 278, Tei-Tow Road, Sec. 2
Hsin-Chu City, Taiwan, R.O.C.

Dated: 2009/07/07

Inventor Signature

Inventor Name: Yu-Ting Lin

Residence Address: 8F-1, No. 523, Nan-Da Road
Hsin-Chu City, Taiwan, R.O.C.

Dated: 2009/06/26

Yu-ting Lin
Inventor Signature
